

SPECIFICATION

ADHESIVE FILM AND METHOD FOR MANUFACTURING ELECTRONIC DEVICE

TECHNICAL FIELD

5 [0001]

The present invention relates to an adhesive film and a method for manufacturing an electronic device.

BACKGROUND ART

10 [0002]

As a technology which is able to reduce the size and weight of electronic devices (for example, semiconductor apparatuses), a fan-out type WLP (wafer level package) is being developed.

In an eWLB (Embedded Wafer Level Ball Grid Array), which is one
15 of the methods for manufacturing a fan-out type WLP, it is possible to adopt a method in which a plurality of electronic components such as semiconductor chips are temporarily fixed in a separated state on an adhesive film attached to a support substrate, and the plurality of electronic components are sealed in a batch with a sealing material.
20 Here, the adhesive film needs to be fixed to the electronic component and the support substrate in the sealing step or the like and needs to be removed from the sealed electronic component and the support substrate after the sealing.

[0003]

25 Examples of a technique related to such a fan-out type WLP manufacturing method include the technique described in Patent

Document 1 (Japanese Patent Laid-Open No. 2011-134811).

[0004]

Patent Document 1 discloses a heat-resistant adhesive sheet for manufacturing a semiconductor apparatus, which is used by being
5 attached when resin-sealing a substrateless semiconductor chip, in which the heat resistant adhesive sheet has a base material layer and an adhesive layer, the adhesive layer has an adhesive force to SUS304 after bonding of 0.5 N/20 mm or more, is cured by a stimulus received until the completion of a resin sealing step, and has a peel
10 force with respect to a package of 2.0 N/20 mm or less.

RELATED DOCUMENT

PATENT DOCUMENT

[0005]

[Patent Document 1] Japanese Patent Laid-Open No. 2011-134811
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SUMMARY OF THE INVENTION

TECHNICAL PROBLEM

[0006]

According to studies by the inventors of the present invention,
20 it is clear that, when an electronic component is arranged on an adhesive film and the electronic component is sealed with a sealing material, a position of the electronic component may be shifted (also referred to below as position shifting of the electronic component).

The present invention was made in view of the above circumstances
25 and provides an adhesive film capable of suppressing position shifting of electronic components in a sealing step.

SOLUTION TO PROBLEM

[0007]

The inventors of the present invention carried out intensive studies in order to achieve the above object. As a result, it was found that, in an adhesive film provided with a base material layer, an adhesive resin layer (A) provided on a first surface side of the base material layer, and an adhesive resin layer (B) provided on a second surface side of the base material layer and in which an adhesive force is decreased by an external stimulus, in which measuring an integrated value of the tacking force of the adhesive resin layer (B), which is measured by a specific method, is effective as a design guideline for an adhesive film for suppressing the position shifting of an electronic component in a sealing step, thereby completing the present invention.

[0008]

According to the present invention, an adhesive film and a method for manufacturing an electronic device illustrated below are provided.

[0009]

[1]

An adhesive film including a base material layer, an adhesive resin layer (A) provided on a first surface side of the base material layer, and an adhesive resin layer (B) provided on a second surface side of the base material layer and in which an adhesive force is decreased by an external stimulus, in which, as measured by method 1, an integrated tacking force value ($F_{2.5}$) of the adhesive resin layer (B) is 1.0 gf/sec or more

at a test speed of 2.5 mm/min and a test temperature of 130°C, and an integrated tacking force value (F_{30}) of the adhesive resin layer (B) is 7.0 gf/sec or more at a test speed of 30 mm/min and a test temperature of 130°C,

5 (method 1) using a tacking tester, a probe is pressed on the adhesive resin layer (B) for 60 seconds under conditions of a probe load of 100 gf and a probe pushing speed of 120 mm/min, then, at a test temperature of 130°C, tack strengths (gf) are respectively measured at test speeds of 2.5 mm/min and 30 mm/min, measurement time
10 is set as a horizontal axis and the tack strength (gf) is set as a vertical axis, integrated values are each calculated from a point where the tack strength starts to rise from 0 to a point where the tack strength becomes 0 again, and the calculated values are respectively set as $F_{2.5}$ and F_{30} .

15 [2]

The adhesive film according to [1],

in which the adhesive film is used for temporarily fixing an electronic component when the electronic component is sealed with a sealing material in an electronic device manufacturing step.

20 [3]

The adhesive film according to [1] or [2],

in which an adhesive force of the adhesive resin layer (B) is decreased by heating at a temperature over 150°C.

[4]

25 The adhesive film according to [3], in which the adhesive resin layer (B) includes at least one selected from a gas generating component and a heat-expandable microsphere.

[5]

The adhesive film according to any one of [1] to [4],
in which a content of at least one selected from a gas generating
components and a heat-expandable microsphere in the adhesive resin
5 layer (A) is 0.1% by mass or less when an entire adhesive resin layer
(A) is 100% by mass.

[6]

The adhesive film according to any one of [1] to [5],
in which the adhesive resin layer (A) includes a (meth)acrylic
10 adhesive resin.

[7]

A method for manufacturing an electronic device including at
least:

a step (1) of preparing a structure having the adhesive film
15 according to any one of [1] to [6], an electronic component attached
to the adhesive resin layer (A) of the adhesive film, and a support
substrate attached to the adhesive resin layer (B) of the adhesive
film;

a step (2) of sealing the electronic component with a sealing
20 material;

a step (3) of peeling the support substrate from the structure
by decreasing an adhesive force of the adhesive resin layer (B) by
applying an external stimulus;

and a step (4) of peeling the adhesive film from the electronic
25 component.

[8]

The method for manufacturing an electronic device according to

[7],

in which the sealing material is an epoxy resin-based sealing material.

5 ADVANTAGEOUS EFFECTS OF INVENTION

[0010]

According to the present invention, it is possible to provide an adhesive film capable of suppressing position shifting of electronic components in a sealing step.

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BRIEF DESCRIPTION OF THE DRAWINGS

[0011]

The object described above and other objects, features, and advantages will be further clarified by the preferable embodiments described below and the accompanying drawings below.

15

[0012]

Fig. 1 is a cross-sectional view schematically showing an example of a structure of an adhesive film of an embodiment according to the present invention.

20

Fig. 2 is a cross-sectional view schematically showing an example of a method for manufacturing an electronic device of an embodiment according to the present invention.

Fig. 3 is a cross-sectional view schematically showing an example of a method for manufacturing an electronic device of an embodiment according to the present invention.

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DESCRIPTION OF EMBODIMENTS

[0013]

A description will be given below of embodiments of the present invention with reference to the drawings. In all the drawings, common reference numerals are given to the same constituent components and description thereof will not be appropriately repeated. In addition, the figures are schematic views and do not match the actual dimensional ratios. In addition, unless otherwise specified, "A to B" in the numerical range represents A or more and B or less. In addition, in the present embodiment, "(meth)acrylic" means acrylic, methacrylic, or both acrylic and methacrylic.

[0014]

1. Adhesive Film

A description will be given below of an adhesive film 50 according to the present embodiment.

Fig. 1 is a cross-sectional view schematically showing an example of the structure of the adhesive film 50 of the embodiment according to the present invention.

[0015]

As shown in Fig. 1, the adhesive film 50 according to the present embodiment is provided with a base material layer 10, an adhesive resin layer (A) provided on a first surface 10A side of the base material layer 10, and an adhesive resin layer (B) provided on a second surface 10B side of the base material layer 10 and in which an adhesive force is decreased by an external stimulus, in which, as measured by method 1, an integrated tacking force value ($F_{2.5}$) of the adhesive resin layer (B) is 1.0 gf/sec or more at a test speed of 2.5 mm/min and a test temperature of 130°C, and an integrated tacking force value

(F_{30}) of the adhesive resin layer (B) is 7.0 gf/sec or more at a test speed of 30 mm/min and a test temperature of 130°C.

(Method 1) Using a tacking tester, a probe is pressed on the adhesive resin layer (B) for 60 seconds under conditions of a probe load of 100 gf and a probe pushing speed of 120 mm/min, then, at a test temperature of 130°C, tack strengths (gf) are respectively measured at test speeds of 2.5 mm/min and 30 mm/min, measurement time is set as a horizontal axis and the tack strength (gf) is set as a vertical axis, integrated values are each calculated from a point where the tack strength starts to rise from 0 to a point where the tack strength becomes 0 again, and the calculated values are respectively set as $F_{2.5}$ and F_{30} .

[0016]

As described above, according to studies by the inventors of the present invention, it is clear that, when an electronic component is arranged on an adhesive film and the electronic component is sealed with a sealing material, the position of the electronic component may be shifted.

[0017]

The inventors of the present invention carried out extensive studies in order to realize an adhesive film which is able to suppress position shifting of electronic components in the sealing step. As a result, it was found for the first time that, in the adhesive film provided with the base material layer 10, the adhesive resin layer (A) provided on the first surface 10A side of the base material layer 10, and the adhesive resin layer (B) provided on the second surface 10B side of the base material layer 10 and in which an adhesive force

is decreased by an external stimulus, measuring the integrated tacking force value ($F_{2.5}$) and the integrated tacking force value (F_{30}) of the adhesive resin layer (B) measured by method 1 is effective as a design guideline for an adhesive film for suppressing position shifting of electronic components in a sealing step.

That is, in the adhesive film 50 according to the present embodiment, setting the integrated tacking force value ($F_{2.5}$) and the integrated tacking force value (F_{30}) of the adhesive resin layer (B) to each be the above lower limit value or more makes it possible to suppress the position shifting of the electronic component in the sealing step.

It is not clear why the use of the adhesive film 50 according to the present embodiment makes it possible to suppress position shifting of electronic components in the sealing step, but the following reasons may be considered.

First, studies by the inventors of the present invention found that, in the step of sealing an electronic component, water and outgas derived from residual volatile components included in the adhesive film, particularly, water and outgas derived from residual volatile components included in the adhesive resin layer on the side to be attached to the support substrate, cause the adhesive film to float and, as a result, causes position shifting of the electronic component. The inventors of the present invention carried out further studies based on the above findings. As a result, it is clear that, with an adhesive film having an integrated tacking force value ($F_{2.5}$) and an integrated tacking force value (F_{30}) of the adhesive resin layer (B), which are measured by method 1 and which are the above lower

limit value or more, respectively, in the step of sealing the electronic component, floating does not easily occur due to the water or outgas derived from the residual volatile components included in the adhesive film, in particular, water or outgas derived from the residual volatile components included in the adhesive resin layer on the side to be attached to the support substrate and, as a result, position shifting of the electronic components does not easily occur. That is, it is considered that, in an adhesive film in which the integrated tacking force value ($F_{2.5}$) and the integrated tacking force value (F_{30}) of the adhesive resin layer (B) are the above lower limit values or more, respectively, in the sealing step, there is unlikely to be an adverse influence due to water or outgas derived from the residual volatile components, and as a result, it is possible to suppress position shifting of the electronic components in the sealing step.

[0018]

In the adhesive film 50 according to the present embodiment, the lower limit of the integrated tacking force value ($F_{2.5}$) is 1.0 gf/sec or more, but, from the viewpoint that it is possible to further suppress position shifting of the electronic component in the sealing step, 1.5 gf/sec or more is preferable, 2.0 gf/sec or more is more preferable, and 2.5 gf/sec or more is even more preferable.

In addition, in the adhesive film 50 according to the present embodiment, from the viewpoint of effectively suppressing adhesive residue on the support substrate side when peeling the support substrate from the adhesive resin layer (B) and obtaining good detachability from the support substrate, the upper limit of the

integrated tacking force value ($F_{2.5}$) is preferably 50.0 gf/sec or less, more preferably 35.0 gf/sec or less, even more preferably 25.0 gf/sec or less, still more preferably 15 gf/sec or less, and particularly preferably 7.5 gf/sec or less.

5 [0019]

In addition, in the adhesive film 50 according to the present embodiment, the lower limit of the integrated tacking force value (F_{30}) is 7.0 gf/sec or more, but, from the viewpoint of being able to further suppress the position shifting of the electronic component
10 in the sealing step, 8.0 gf/sec or more is preferable, 9.0 gf/sec or more is more preferable, and 10.0 gf/sec or more is even more preferable.

In addition, in the adhesive film 50 according to the present embodiment, from the viewpoint of effectively suppressing adhesive
15 residue on the support substrate side when peeling the support substrate from the adhesive resin layer (B) and obtaining good detachability from the support substrate, the upper limit of the integrated tacking force value (F_{30}) is preferably 150.0 gf/sec or less, more preferably 100.0 gf/sec or less, even more preferably 80.0
20 gf/sec or less, still more preferably 50.0 gf/sec or less, and particularly preferably 25.0 gf/sec or less.

[0020]

In the adhesive film 50 according to the present embodiment, it is possible to control the integrated tacking force value ($F_{2.5}$)
25 and the integrated tacking force value (F_{30}), for example, by controlling the type and blending ratio of each component forming the adhesive resin layer (B) and the type and content ratio of each

monomer in the adhesive resin forming the adhesive resin layer (B). More specifically, it is presumed that the hardness of the adhesive resin layer (B) and the volatile components included in the adhesive resin layer (B) have an influence and there is a tendency for the amount of a cross-linking agent (B2) and the amount of water and residual solvent included in the adhesive film 50 (particularly the adhesive resin layer (B)) to have an influence. Accordingly, it is possible to control the integrated tacking force value ($F_{2.5}$) and the integrated tacking force value (F_{30}) in the above range by controlling the amount and number of functional groups of the cross-linking agent (B2), the water included in the adhesive film 50 (particularly the adhesive resin layer (B)), the amount of residual volatile components such as residual solvent, and the like, which will be described below.

[0021]

From the viewpoint of the balance between mechanical properties and handleability, the total thickness of the adhesive film 50 according to the present embodiment is preferably 10 μm or more and 1000 μm or less, and more preferably 20 μm or more and 500 μm or less.

[0022]

It is possible to use the adhesive film 50 according to the present embodiment, for example, in a film or the like for temporarily fixing electronic components in an electronic device manufacturing step, and particularly, suitable use is possible as a film for temporarily fixing electronic components in a manufacturing step for a fan-out type WLP.

[0023]

Next, a description will be given of each layer forming the

adhesive film 50 according to the present embodiment.

[0024]

<Base Material Layer>

The base material layer 10 is a layer provided for the purpose
5 of improving properties such as the handleability, mechanical
properties, and heat resistance of the adhesive film 50.

The base material layer 10 is not particularly limited and
examples thereof include a resin film.

It is possible to use a known thermoplastic resin as the resin
10 forming the resin film. Examples thereof include one type or two
or more types selected from polyolefins such as polyethylene,
polypropylene, poly(4-methyl-1-pentene), and poly(1-butene);
polyesters such as polyethylene terephthalate, polybutylene
terephthalate, and polyethylene naphthalate; polyamides such as
15 nylon-6, nylon-66, and polymethaxylene adipamide; polyacrylates;
polymethacrylates; polyvinyl chloride; polyvinylidene chloride;
polyimides; polyetherimides; ethylene/vinyl acetate copolymers;
polyacrylonitrile; polycarbonates; polystyrenes; ionomers;
polysulfones; polyethersulfones; polyphenylene ether, and the like.

20 Among the above, from the viewpoint of excellent balance of
transparency, mechanical strength, price, and the like, one type or
two or more types selected from polypropylene, polyethylene
terephthalate, polyethylene naphthalate, polyamide, and polyimide
are preferable, and at least one type selected from polyethylene
25 terephthalate and polyethylene naphthalate is more preferable.

[0025]

The base material layer 10 may be a single layer or two or more

types of layers.

In addition, the form of the resin film used to form the base material layer 10 may be a stretched film, or may be a uniaxially or biaxially stretched film; however, from the viewpoint of improving the mechanical strength of the base material layer 10, the film is preferably a uniaxially or biaxially stretched film.

[0026]

From the viewpoint of obtaining good film properties, the thickness of the base material layer 10 is preferably 1 μm or more and 500 μm or less, more preferably 5 μm or more and 300 μm or less, and even more preferably 10 μm or more and 250 μm or less.

The base material layer 10 may be surface-treated in order to improve the adhesion with other layers. Specifically, a corona treatment, a plasma treatment, an undercoat treatment, a primer coat treatment, or the like may be performed.

[0027]

<Adhesive Resin Layer (A)>

The adhesive resin layer (A) is a layer provided on one surface side of the base material layer 10, and, for example, is a layer for contacting the surface of the electronic component to temporarily fix the electronic component when the electronic component is sealed with a sealing material in the electronic device manufacturing step.

[0028]

The adhesive resin layer (A) includes an adhesive resin (A1).

Examples of the adhesive resin (A1) include (meth)acrylic adhesive resin (a), a silicone-based adhesive resin, a urethane-based adhesive resin, an olefin-based adhesive resin, a styrene-based

adhesive resin, and the like.

Among the above, the (meth)acrylic adhesive resin (a) is preferable from the viewpoint of facilitating the adjustment of the adhesive force and the like.

5 [0029]

As the adhesive resin layer (A), it is also possible to use a radiation-cross-linking adhesive resin layer in which the adhesive force is decreased by radiation. The radiation cross-linking adhesive resin layer is cross-linked by the irradiation of radiation
10 and the adhesive force is significantly reduced, thus, the adhesive film 50 is easily peeled from the electronic component. Examples of the radiation include ultraviolet rays, electron beams, infrared rays, and the like.

As the radiation cross-linking adhesive resin layer, an
15 ultraviolet cross-linking adhesive resin layer is preferable.

[0030]

Examples of the (meth)acrylic adhesive resin (a) used in the adhesive resin layer (A) include a copolymer including a (meth)acrylic acid alkyl ester monomer unit (a1) and a monomer unit
20 (a2) having a functional group capable of reacting with a cross-linking agent.

In the present embodiment, the (meth)acrylic acid alkyl ester means an acrylic acid alkyl ester, a methacrylic acid alkyl ester, or a mixture thereof.

25 [0031]

It is possible to obtain the (meth)acrylic adhesive resin (a) according to the present embodiment, for example, by copolymerizing

a monomer mixture including the (meth)acrylic acid alkyl ester monomer (a1) and the monomer (a2) having a functional group capable of reacting with a cross-linking agent.

[0032]

5 Examples of the monomer (a1) forming the (meth)acrylic acid alkyl ester monomer unit (a1) include a (meth)acrylic acid alkyl ester having an alkyl group having approximately 1 to 12 carbon atoms. A (meth)acrylic acid alkyl ester having an alkyl group having 1 to 8 carbon atoms is preferable. Specific examples thereof include methyl
10 acrylate, methyl methacrylate, ethyl acrylate, ethyl methacrylate, butyl acrylate, butyl methacrylate, 2-ethylhexyl acrylate, 2-ethylhexyl methacrylate, and the like. These may be used alone or in a combination of two or more types.

 In the (meth)acrylic adhesive resin (a) according to the present
15 embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (a) is 100% by mass, the content of the (meth)acrylic acid alkyl ester monomer unit (a1) is preferably 10% by mass or more and 98.9% by mass or less, more preferably 50% by mass or more and 97% by mass or less, and even more preferably 85%
20 by mass or more and 95% by mass or less.

[0033]

 Examples of the monomer (a2) forming the monomer (a2) having a functional group capable of reacting with the cross-linking agent include acrylic acid, methacrylic acid, itaconic acid, mesaconic acid,
25 citraconic acid, fumaric acid, maleic acid, itaconic acid monoalkyl ester, mesaconic acid monoalkyl ester, citraconic acid monoalkyl ester, fumaric acid monoalkyl ester, maleic acid monoalkyl ester,

glycidyl acrylate, glycidyl methacrylate, 2-hydroxyethyl acrylate, 2-hydroxyethyl methacrylate, acrylamide, methacrylamide, tert-butylaminoethyl acrylate, tert-butylaminoethyl methacrylate, and the like. Preferable are acrylic acid, methacrylic acid, 2-hydroxyethyl acrylate, 2-hydroxyethyl methacrylate, acrylamide, methacrylamide, and the like. These may be used alone or in a combination of two or more types.

In the (meth)acrylic adhesive resin (a) according to the present embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (a) is 100% by mass, the content of the monomer unit (a2) is preferably 1% by mass or more and 40% by mass or less, more preferably 1% by mass or more and 20% by mass or less, and even more preferably 1% by mass or more and 10% by mass or less. [0034]

The (meth)acrylic adhesive resin (a) according to the present embodiment may, in addition to the monomer unit (a1) and the monomer unit (a2), further include a bifunctional monomer unit (a3) and a specific comonomer (referred to below as a polymerizable surfactant) unit having properties as a surfactant.

The polymerizable surfactant has a property of copolymerizing with the monomer (a1), the monomer (a2), and the monomer (a3), and also has an action as an emulsifier in the case of emulsion polymerization. [0035]

Examples of the monomer (a3) forming the bifunctional monomer unit (a3) include allyl methacrylate, allyl acrylate, divinylbenzene, vinyl methacrylate, vinyl acrylate, trimethylolpropane

tri(meth)acrylate, pentaerythritol tri(meth)acrylate, dipentaerythritol hexa(meth)acrylate, tetraethylene glycol di(meth)acrylate, or, for example, monomers in which a main chain structure is a propylene glycol type with diacrylate or dimethacrylate at both ends (for example, manufactured by NOF Corp., trade name: PDP-200, PDP-400, ADP-200, and ADP-400), tetramethylene glycol type monomers (for example, manufactured by NOF Corp.; trade name: ADT-250, ADT-850), mixtures thereof (for example, manufactured by NOF Corp., trade name: ADET-1800 and ADPT-4000), and the like.

10 [0036]

In the (meth)acrylic adhesive resin (a) according to the present embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (a) is 100% by mass, the content of the monomer unit (a3) is preferably 0.1% by mass or more and 30% by mass or less, more preferably 0.1% by mass or more and 15% by mass or less, even more preferably 0.1% by mass or more and 20% by mass or less, and particularly preferably 0.1% by mass or more and 5% by mass or less.

[0037]

20 Examples of the polymerizable surfactant include a surfactant in which a polymerizable 1-propenyl group is introduced into a benzene ring of polyoxyethylene nonylphenyl ether (manufactured by DKS Co., Ltd.; trade name: Aqualon RN-10, RN-20, RN-30, RN-50, and the like), a surfactant in which a polymerizable 1-propenyl group is introduced into a benzene ring of ammonium salt of sulfuric acid ester of polyoxyethylene nonylphenyl ether (manufactured by DKS Co., Ltd.; trade name: Aqualon HS-10, HS-20, HS-1025, and the like), and a

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sulfosuccinate diester-based surfactant having a polymerizable double bond in the molecule (manufactured by Kao Corp.; trade name: Latemul S-120A, S-180A, and the like), or the like.

In the (meth)acrylic adhesive resin (a) according to the present
5 embodiment, when the total of all the monomer units in the
(meth)acrylic adhesive resin (a) is 100% by mass, the content of the
polymerizable surfactant is preferably 0.1% by mass or more and 30%
by mass or less, more preferably 0.1% by mass or more and 15% by mass
or less, even more preferably 0.1% by mass or more and 20% by mass
10 or less, and particularly preferably 0.1% by mass or more and 5% by
mass or less.

[0038]

The (meth)acrylic adhesive resin (a) according to the present
embodiment may further include a monomer unit formed of a monomer
15 having a polymerizable double bond such as vinyl acetate,
acrylonitrile, or styrene, as necessary.

[0039]

Examples of the polymerization reaction mechanism of the
(meth)acrylic adhesive resin (a) according to the present embodiment
20 include radical polymerization, anionic polymerization, cationic
polymerization, and the like. In consideration of the manufacturing
cost of the (meth)acrylic adhesive resin (a), the influence of the
functional group of the monomer, the influence of ions on the surface
of the electronic component, and the like, it is preferable to carry
25 out the polymerization by radical polymerization.

When polymerizing by a radical polymerization reaction,
examples of radical polymerization initiators include organic

peroxides such as benzoyl peroxide, di-t-butyl peroxide, dicumyl peroxide, 3,3,5-trimethylhexanoyl peroxide, di-2-ethylhexylperoxy dicarbonate, methyl ethyl ketone peroxide, t-butylperoxyphthalate, t-butylperoxybenzoate, di-t-butylperoxyacetate,
 5 t-butylperoxyisobutyrate, t-butylperoxy-2-hexanoate, t-butylperoxy-2-ethylhexanoate, t-butylperoxy-3,5,5-trimethylhexanoate, acetyl peroxide, isobutyryl peroxide, octanoyl peroxide, t-butyl peroxide, and di-t-amyl peroxide; inorganic peroxides such as ammonium persulfate,
 10 potassium persulfate, and sodium persulfate; azo compounds such as 2,2'-azobisisobutyronitrile, 2,2'-azobis-2-methylbutyronitrile, and 4,4'-azobis-4-cyanovaleric acid.

[0040]

In a case of polymerizing by an emulsion polymerization method,
 15 among these radical polymerization initiators, inorganic peroxides such as water-soluble ammonium persulfate, potassium persulfate, and sodium persulfate, and azo compounds having a carboxyl group in the molecule such as water-soluble 4,4'-azobis-4-cyanovaleric acid are preferable. Considering the influence of ions on the surface of the
 20 electronic components, ammonium persulfate and azo compounds having a carboxyl group in the molecule such as 4,4'-azobis-4-cyanovaleric acid are more preferable, and azo compounds having a carboxyl group in the molecule such as 4,4'-azobis-4-cyanovaleric acid are particularly preferable.

25 [0041]

The adhesive resin layer (A) according to the present embodiment preferably further includes a cross-linking agent (A2) having two

or more cross-linkable functional groups in one molecule, in addition to the adhesive resin (A1).

A cross-linking agent (A2) having two or more cross-linkable functional groups in one molecule is used to react with the functional group of the adhesive resin (A1) and adjust the adhesive force and aggregating force.

Examples of such a cross-linking agent (A2) include epoxy-based compounds such as sorbitol polyglycidyl ether, polyglycerol polyglycidyl ether, pentaerythritol polyglycidyl ether, diglycerol polyglycidyl ether, glycerol polyglycidyl ether, neopentyl glycol diglycidyl ether, and resorcin diglycidyl ether; isocyanate-based compounds such as tetramethylene diisocyanate, hexamethylene diisocyanate, toluene diisocyanate 3 adducts of trimethylolpropane, polyisocyanate, diphenylmethane diisocyanate, and tolylene diisocyanate; aziridine-based compounds such as trimethylolpropane-tri- β -aziridinypropionate, tetramethylolmethane-tri- β -aziridinypropionate, N,N'-diphenylmethane-4,4'-bis(1-aziridinecarboxamide), N,N'-hexamethylene-1,6-bis(1-aziridinecarboxamide), N,N'-toluene-2,4-bis(1-aziridinecarboxamide), and trimethylolpropane-tri- β -(2-methylaziridine) propionate; tetrafunctional epoxy-based compounds such as N,N,N',N'-tetraglycidyl-m-xylenediamine and 1,3-bis(N,N'-diglycidylaminomethyl) cyclohexane; and melamine-based compounds such as hexamethoxymethylolmelamine.

These may be used alone or in a combination of two or more types.

Among the above, it is preferable to include one type or two

or more types selected from an epoxy-based compound, an isocyanate-based compound, and an aziridine-based compound.

[0042]

The content of the cross-linking agent (A2) is usually preferably in a range in which the number of functional groups in the cross-linking agent (A2) does not exceed the number of functional groups in the adhesive resin (A1). However, in a case where a functional group is newly generated in the cross-linking reaction, a case where the cross-linking reaction is slow, or the like, the content thereof may be greater as necessary.

From the viewpoint of improving the balance between the heat resistance and the adhesive force of the adhesive resin layer (A), the content of the cross-linking agent (A2) in the adhesive resin layer (A) is preferably 0.1 parts by mass or more and 15 parts by mass or less with respect to 100 parts by mass of the adhesive resin (A1).

[0043]

When the entire adhesive resin layer (A) is 100% by mass, the total content of the adhesive resin (A1) and the cross-linking agent (A2) in the adhesive resin layer (A) is preferably 50% by mass or more and 100% by mass or less, more preferably 70% by mass or more and 100% by mass or less, even more preferably 90% by mass or more and 100% by mass or less, and particularly preferably 95% by mass or more and 100% by mass or less. Due to this, it is possible to further suppress adhesive residue on the electronic component side when the adhesive film is peeled off from the electronic component.

[0044]

The thickness of the adhesive resin layer (A) is not particularly limited, but is, for example, preferably 1 μm or more and 100 μm or less, and more preferably 3 μm or more and 50 μm or less.

[0045]

5 It is possible to form the adhesive resin layer (A), for example, by coating an adhesive on the base material layer 10. The adhesive may be dissolved in a solvent and coated as a coating solution, coated as an aqueous emulsion, or directly coated as a liquid adhesive.

10 Among the above, an aqueous emulsion coating solution is preferable. Examples of the aqueous emulsion coating solution include coating solutions in which the (meth)acrylic adhesive resin (a), a silicone-based adhesive resin, a urethane-based adhesive resin, an olefin-based adhesive resin, a styrene-based adhesive resin, or the like is dispersed in water.

15 An adhesive coating solution dissolved in an organic solvent may be used. The organic solvent is not particularly limited and may be appropriately selected from known organic solvents in consideration of solubility and drying time. Examples of organic solvents include ester-based organic solvents such as ethyl acetate
20 and methyl acetate; ketone-based organic solvents such as acetone and MEK; aromatic-based organic solvents such as benzene, toluene, and ethylbenzene; linear or cyclic aliphatic-based organic solvents such as heptane, hexane, and cyclohexane; alcohol-based organic solvents such as isopropanol and butanol. Ethyl acetate and toluene
25 are preferable as the organic solvent. These solvents may be used alone as one type or used in a mixture of two or more types.

As a method for coating the adhesive coating solution, it is

possible to adopt a coating method known in the related art, for example, a roll coater method, a reverse roll coater method, a gravure roll method, a bar coating method, a comma coater method, a die coater method, or the like. The drying conditions of the coated adhesive
5 are not particularly limited, but, generally, drying for 10 seconds to 10 minutes in a temperature range of 80 to 200°C is preferable. More preferably, drying is performed at 80 to 170°C for 15 seconds to 5 minutes. In order to sufficiently accelerate the cross-linking reaction between the cross-linking agent and the adhesive, the
10 adhesive coating solution may be heated at 40 to 80°C for approximately 5 to 300 hours after drying.

In addition, the base material layer 10 and the adhesive resin layer (A) may be formed by coextrusion molding, or the film-shaped base material layer 10 and the film-shaped adhesive resin layer (A)
15 may be formed by laminating (laminated).

[0046]

<Adhesive Resin Layer (B)>

The adhesive film 50 according to the present embodiment is provided with an adhesive resin layer (B) on the second surface 10B
20 side of the base material layer 10 on the opposite side to the first surface 10A, the adhesive force of which is decreased by an external stimulus.

Due to this, it is possible to easily peel the adhesive film 50 from the support substrate 80 by applying an external stimulus.

25 Here, examples of the adhesive resin layer (B), the adhesive force of which is decreased by an external stimulus, include a heat-peelable adhesive resin layer, the adhesive force of which is

decreased by heating, and a radiation-peelable adhesive resin layer, the adhesive force of which is decreased by radiation, and the like. Among the above, a heat-peelable adhesive resin layer, the adhesive force of which is decreased by heating, is preferable.

5 Examples of the heat-peelable adhesive resin layer include adhesive resin layers formed of a heat-expandable adhesive including a gas generating component, a heat-expandable adhesive including heat-expandable microspheres capable of expanding to decrease the adhesive force, a heat-expandable adhesive, the adhesive force of
10 which is decreased by the cross-linking reaction of the adhesive components due to heat, or the like.

[0047]

 In the present embodiment, the heat-expandable adhesive used in the adhesive resin layer (B) is an adhesive, the adhesive force
15 of which is decreased or lost by heating at a temperature over 150°C, for example. For example, it is possible to select a material which does not peel at a temperature of 150°C or lower and which does peel at a temperature over 150°C and the heat-expandable adhesive preferably has an adhesive force such that the adhesive film 50 does
20 not peel from the support substrate 80 during the electronic device manufacturing step.

 Here, it is possible to evaluate whether the adhesive force is decreased or lost by heating at a temperature over 150°C, for example, by attaching the adhesive resin layer (B) side to a stainless steel
25 plate, performing a heat treatment at 140°C for 1 hour, then heating for 2 minutes at a temperature over 150°C and measuring the peel force from the stainless steel plate. The specific heating temperature

when heating at a temperature over 150°C is set to a temperature higher than the temperature at which the gas is generated or the temperature at which the heat-expandable microspheres are heat-expanded and is appropriately set depending on the gas to be generated or the type of heat-expandable microspheres. In the present embodiment, the loss of adhesive force means, for example, a case where the 180° peel force measured under the conditions of 23°C and a tensile speed of 300 mm/min becomes less than 0.5 N/25 mm.

[0048]

As the gas generating component used in the heat-expandable adhesive, for example, it is possible to use an azo compound, an azide compound, a Meldrum's acid derivative, or the like. In addition, it is also possible to use inorganic foaming agents such as ammonium carbonate, ammonium hydrogencarbonate, sodium hydrogencarbonate, ammonium nitrite, sodium borohydride, and various azides, or water; salts of fluoroalkane-based compounds such as trichloromonofluoromethane and dichloromonofluoromethane; azo-based compounds such as azobisisobutyronitrile, azodicarbonamide, and barium azodicarboxylate; hydrazine-based compounds such as paratoluenesulfonyl hydrazide, diphenylsulfone-3,3'-disulfonylhydrazide, 4,4'-oxybis(benzenesulfonyl hydrazide) and allylbis(sulfonylhydrazide); semicarbazide-based compounds such as p-toluylenesulfonyl semicarbazide, and 4,4'-oxybis(benzenesulfonyl semicarbazide); triazole-based compounds such as 5-morpholyl-1,2,3,4-thiatriazole; organic foaming agents such as N-nitroso compounds such as N,N'-dinitrosopentamethylenetetramine,

and N,N'-dimethyl-N,N'-dinitrosoterephthalamide, and the like. The gas generating component may be added to the adhesive resin (B1) or may be directly bonded to the adhesive resin (B1).

[0049]

5 As the heat-expandable microspheres used for the heat-expandable adhesive, for example, it is possible to use a microencapsulated foaming agent. Examples of such heat-expandable microspheres include microspheres in which a substance that is easily gasified and expanded by heating such as isobutane, propane, and
10 pentane is sealed in a shell having elasticity, or the like. Examples of the material forming the shell include vinylidene chloride-acrylonitrile copolymer, polyvinyl alcohol, polyvinyl butyral, polymethyl methacrylate, polyacrylonitrile, polyvinylidene chloride, polysulfone, and the like. It is possible
15 to manufacture heat-expandable microspheres by, for example, a coacervation method, an interfacial polymerization method, or the like.

It is possible to add heat-expandable microspheres to the adhesive resin.

20 [0050]

It is possible to appropriately set the content of at least one type selected from the gas generating component and the heat-expandable microspheres according to the expansion ratio and the decrease in adhesive force of the heat-peelable adhesive resin
25 layer (B) and the like without being particularly limited; however, for example, with respect to 100 parts by mass of the adhesive resin (B1) in the heat-peelable adhesive resin layer (B), the content is,

for instance, 1 part by mass or more and 150 parts by mass or less, preferably 10 parts by mass or more and 130 parts by mass or less, and more preferably 12 parts by mass or more and 100 parts by mass or less.

5 It is preferable to implement the design such that the temperature at which gas is generated or the temperature at which the heat-expandable microspheres heat-expand is over 150°C.

[0051]

Examples of the adhesive resin (B1) forming the heat-expandable
10 adhesive include (meth)acrylic resin (b), urethane-based resin, silicone-based resin, polyolefin-based resin, polyester-based resin, polyamide-based resin, fluorine resin-based resins, styrene-diene block copolymer-based resins, and the like. Among these, the (meth)acrylic resin (b) is preferable.

15 [0052]

Examples of the (meth)acrylic adhesive resin (b) used in the adhesive resin layer (B) include a copolymer including the (meth)acrylic acid alkyl ester monomer unit (b1) and the monomer unit (b2) having a functional group capable of reacting with a
20 cross-linking agent.

In the present embodiment, (meth)acrylic acid alkyl ester means acrylic acid alkyl ester, methacrylic acid alkyl ester, or a mixture thereof.

[0053]

25 It is possible to obtain the (meth)acrylic adhesive resin (b) according to the present embodiment, for example, by copolymerizing a monomer mixture including a (meth)acrylic acid alkyl ester monomer

(b1) and a monomer (b2) having a functional group capable of reacting with a cross-linking agent.

[0054]

Examples of the monomer (b1) forming the (meth)acrylic acid alkyl ester monomer unit (b1) include a (meth)acrylic acid alkyl ester having an alkyl group having approximately 1 to 12 carbon atoms. A (meth)acrylic acid alkyl ester having an alkyl group having 1 to 8 carbon atoms is preferable. Specific examples thereof include methyl acrylate, methyl methacrylate, ethyl acrylate, ethyl methacrylate, butyl acrylate, butyl methacrylate, 2-ethylhexyl acrylate, 2-ethylhexyl methacrylate, and the like. These may be used alone or in a combination of two or more types.

In the (meth)acrylic adhesive resin (b) according to the present embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (b) is 100% by mass, the content of the (meth)acrylic acid alkyl ester monomer unit (b1) is preferably 10% by mass or more and 98.9% by mass or less, more preferably 50% by mass or more and 97% by mass or less, and even more preferably 85% by mass or more and 95% by mass or less.

[0055]

Examples of the monomer (b2) forming the monomer (b2) having a functional group capable of reacting with the cross-linking agent include acrylic acid, methacrylic acid, itaconic acid, mesaconic acid, citraconic acid, fumaric acid, maleic acid, itaconic acid monoalkyl ester, mesaconic acid monoalkyl ester, citraconic acid monoalkyl ester, fumaric acid monoalkyl ester, maleic acid monoalkyl ester, glycidyl acrylate, glycidyl methacrylate, 2-hydroxyethyl acrylate,

2-hydroxyethyl methacrylic acid, acrylamide, methacrylamide, tert-butylaminoethyl acrylate, tert-butylaminoethyl methacrylate, and the like. Preferable examples are acrylic acid, methacrylic acid, 2-hydroxyethyl acrylate, 2-hydroxyethyl methacrylic acid, acrylamide, methacrylamide, and the like. These may be used alone or in a combination of two or more types.

In the (meth)acrylic adhesive resin (b) according to the present embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (b) is 100% by mass, the content of the monomer unit (b2) is preferably 1% by mass or more and 40% by mass or less, more preferably 1% by mass or more and 20% by mass or less, and even more preferably 1% by mass or more and 10% by mass or less. [0056]

The (meth)acrylic adhesive resin (b) according to the present embodiment may further include a bifunctional monomer unit (b3) and a specific comonomer (referred to below as a polymerizable surfactant) unit having a property as a surfactant in addition to the monomer unit (b1) or the monomer unit (b2).

The polymerizable surfactant has a property of copolymerizing with the monomer (b1), the monomer (b2), and the monomer (b3), and has an action as an emulsifier in a case of emulsion polymerization. [0057]

Examples of the monomer (b3) forming the bifunctional monomer unit (b3) include allyl methacrylate, allyl acrylate, divinylbenzene, vinyl methacrylate, vinyl acrylate, trimethylolpropane tri(meth)acrylate, pentaerythritol tri(meth)acrylate, dipentaerythritol hexa(meth)acrylate, tetraethylene glycol

di(meth)acrylate, or, for example, monomers in which a main chain structure is a propylene glycol type with diacrylate or dimethacrylate at both ends (for example, manufactured by NOF Corp., trade name: PDP-200, PDP-400, ADP-200, and ADP-400), tetramethylene glycol type monomers (for example, manufactured by NOF Corp.; trade name: ADT-250, ADT-850), mixtures thereof (for example, manufactured by NOF Corp., trade name: ADET-1800 and ADPT-4000), and the like.
[0058]

In the (meth)acrylic adhesive resin (b) according to the present embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (b) is 100% by mass, the content of the monomer unit (b3) is preferably 0.1% by mass or more and 30% by mass or less, more preferably 0.1% by mass or more and 15% by mass or less, even more preferably 0.1% by mass or more and 20% by mass or less, and particularly preferably 0.1% by mass or more and 5% by mass or less.
[0059]

Examples of the polymerizable surfactant include a surfactant in which a polymerizable 1-propenyl group is introduced into a benzene ring of polyoxyethylene nonylphenyl ether (manufactured by DKS Co., Ltd.; trade name: Aqualon RN-10, RN-20, RN-30, RN-50, and the like), a surfactant in which a polymerizable 1-propenyl group is introduced into a benzene ring of ammonium salt of sulfuric acid ester of polyoxyethylene nonylphenyl ether (manufactured by DKS Co., Ltd.; trade name: Aqualon HS-10, HS-20, HS-1025, and the like), and a sulfosuccinate diester-based surfactant having a polymerizable double bond in the molecule (manufactured by Kao Corp.; trade name:

Latemul S-120A, S-180A, and the like), or the like.

In the (meth)acrylic adhesive resin (b) according to the present embodiment, when the total of all the monomer units in the (meth)acrylic adhesive resin (b) is 100% by mass, the content of the polymerizable surfactant is preferably 0.1% by mass or more and 30% by mass or less, more preferably 0.1% by mass or more and 15% by mass or less, even more preferably 0.1% by mass or more and 20% by mass or less, and particularly preferably 0.1% by mass or more and 5% by mass or less.

10 [0060]

The (meth)acrylic adhesive resin (b) according to the present embodiment may further contain, as necessary, a monomer unit formed of a monomer having a polymerizable double bond such as vinyl acetate, acrylonitrile, or styrene.

15 [0061]

Examples of the polymerization reaction mechanism of the (meth)acrylic adhesive resin (b) according to the present embodiment include radical polymerization, anionic polymerization, cationic polymerization, and the like. In consideration of the manufacturing cost of the (meth)acrylic adhesive resin (b), the influence of the functional group of the monomer, the influence of ions on the surface of the electronic component, and the like, it is preferable to carry out the polymerization by radical polymerization.

When polymerizing by a radical polymerization reaction, examples of radical polymerization initiators include organic peroxides such as benzoyl peroxide, di-t-butyl peroxide, dicumyl peroxide, 3,3,5-trimethylhexanoyl peroxide, di-2-ethylhexylperoxy

25

dicarbonate, methyl ethyl ketone peroxide, t-butylperoxyphthalate, t-butylperoxybenzoate, di-t-butylperoxyacetate, t-butylperoxyisobutyrate, t-butylperoxy-2-hexanoate, t-butylperoxy-2-ethylhexanoate, 5 t-butylperoxy-3,5,5-trimethylhexanoate, acetyl peroxide, isobutyryl peroxide, octanoyl peroxide, t-butyl peroxide, and di-t-amyl peroxide; inorganic peroxides such as ammonium persulfate, potassium persulfate, and sodium persulfate; and azo compounds such as 2,2'-azobisisobutyronitrile, 2,2'-azobis-2-methylbutyronitrile, 10 and 4,4'-azobis-4-cyanovaleric acid.

[0062]

In a case of polymerizing by an emulsion polymerization method, among these radical polymerization initiators, inorganic peroxides such as water-soluble ammonium persulfate, potassium persulfate, and 15 sodium persulfate, and, similarly, azo compounds having a carboxyl group in the molecule such as water-soluble 4,4'-azobis-4-cyanovaleric acid are preferable. Considering the influence of ions on the surface of the electronic components, ammonium persulfate and azo compounds having a carboxyl group in the 20 molecule such as 4,4'-azobis-4-cyanovaleric acid are more preferable, and azo compounds having a carboxyl group in the molecule such as 4,4'-azobis-4-cyanovaleric acid are particularly preferable.

[0063]

From the viewpoint of more stable peeling from the support 25 substrate, the adhesive resin layer (B) according to the present embodiment preferably further includes a cross-linking agent (B2) having two or more cross-linkable functional groups in a molecule

in addition to the adhesive resin (B1).

A cross-linking agent (B2) having two or more cross-linkable functional groups in one molecule is used to adjust the adhesive force and aggregating force by reacting with the functional group of the
5 adhesive resin (B1).

Examples of the cross-linking agent (B2) include epoxy-based compounds such as sorbitol polyglycidyl ether, polyglycerol polyglycidyl ether, pentaerythritol polyglycidyl ether, diglycerol polyglycidyl ether, glycerol polyglycidyl ether, neopentyl glycol
10 diglycidyl ether, and resorcin diglycidyl ether; isocyanate-based compounds such as tetramethylene diisocyanate, hexamethylene diisocyanate, toluene diisocyanate 3 adducts of trimethylolpropane, polyisocyanate, diphenylmethane diisocyanate, and tolylene diisocyanate; aziridine-based compounds such as
15 trimethylolpropane-tri- β -aziridinypropionate, tetramethylolmethane-tri- β -aziridinypropionate, N,N'-diphenylmethane-4,4'-bis(1-aziridinecarboxamide), N,N'-hexamethylene-1,6-bis(1-aziridinecarboxamide), N,N'-toluene-2,4-bis(1-aziridinecarboxamide), and
20 trimethylolpropane-tri- β -(2-methylaziridine) propionate; tetrafunctional epoxy-based compounds such as N,N,N',N'-tetraglycidyl-m-xylenediamine and 1,3-bis(N,N'-diglycidylaminomethyl) cyclohexane; and melamine-based compounds such as hexamethoxymethylolmelamine, and
25 the like. These may be used alone or in a combination of two or more types.

Among the above, it is preferable to include one type or two

or more types selected from epoxy-based compounds, isocyanate-based compounds, and aziridine-based compounds.

[0064]

The content of the cross-linking agent (B2) is usually
5 preferably in an approximate range in which the number of functional groups in the cross-linking agent (B2) does not exceed the number of functional groups in the adhesive resin (B1). However, in a case where a functional group is newly generated in the cross-linking reaction, a case where the cross-linking reaction is slow, or the
10 like, the content thereof may be greater as necessary.

From the viewpoint of more stable peeling from the support substrate, the content of the cross-linking agent (B2) in the adhesive resin layer (B) is preferably 0.5 parts by mass or more and 4.0 parts by mass or less with respect to 100 parts by mass of the adhesive
15 resin (B1), and more preferably 1.0 part by mass or more and 3.0 parts by mass or less.

[0065]

When the entire adhesive resin layer (B) is 100% by mass, the total content of the adhesive resin (B1) and the cross-linking agent
20 (B2) in the adhesive resin layer (B) is preferably 50% by mass or more and 100% by mass or less, more preferably 70% by mass or more and 100% by mass or less, even more preferably 90% by mass or more and 100% by mass or less, and particularly preferably 95% by mass or more and 100% by mass or less. Due to this, it is possible to
25 further suppress position shifting of the electronic component in the sealing step.

[0066]

When the total of the adhesive resin layer (B) is 100% by mass, the total content of at least one type selected from the adhesive resin (B1), the cross-linking agent (B2), and the gas generating component and the heat-expandable microspheres in the adhesive resin layer (B) is preferably 50% by mass or more and 100% by mass or less, more preferably 70% by mass or more and 100% by mass or less, even more preferably 90% by mass or more and 100% by mass or less, and particularly preferably 95% by mass or more and 100% by mass or less. [0067]

In addition, from the viewpoint of stably holding the electronic component on the adhesive resin layer (A) when an external stimulus is applied so as to decrease the adhesive force of the adhesive resin layer (B) and peel the support substrate from the adhesive resin layer (B), in the adhesive film 50 according to the present embodiment, when the total of the adhesive resin layer (A) is 100% by mass, the content of at least one type selected from the gas generating component and the heat-expandable microspheres in the adhesive resin layer (A) is preferably 0.1% by mass or less, more preferably 0.05% by mass or less, even more preferably 0.01% by mass or less, and particularly preferably such that at least one type selected from a gas generating component and heat-expandable microspheres is not included in the adhesive resin layer (A).

[0068]

From the viewpoint of improving the adhesion to the support substrate, the adhesive resin layer (B) according to the present embodiment preferably includes a tackifying resin in addition to the adhesive resin (B1). It is preferable for the adhesive resin layer

(B) to contain a tackifying resin in order to easily adjust the adhesion with the support substrate at around room temperature. The tackifying resin preferably has a softening point of 100°C or higher. Specific examples of the tackifying resin include rosin-based resins
5 such as rosin-based derivatives subjected to esterification and the like; terpene-based resins such as α -pinene-based, β -pinene-based, dipentene-based, and terpene-phenol-based resins; natural rosins such as gum-based, wood-based, and tall oil-based rosins; hydrogenated, disproportionated, polymerized, maleated, petroleum
10 resins in these natural rosins; coumarone-indene resins and the like.
[0069]

Among the above, examples having a softening point in a range of 100 to 160°C are more preferable, and examples having a softening point in a range of 120 to 150°C are particularly preferable. When
15 the tackifying resin having a softening point in the range described above is used, not only is the contamination and adhesive residue on the support substrate small, but it is possible to further improve the adhesion to the support substrate in a working environment. Further, when a polymerized rosin ester-based tackifying resin is
20 used as the tackifying resin, not only is contamination and adhesive residue on the support substrate small, but the adhesion with the support substrate in an environment of 80 to 130°C also improves and, after expansion of the heat-expandable microspheres, it is possible to more easily carry out the peeling from the support substrate.
25 [0070]

The blending ratio of the tackifying resin may be appropriately selected such that it is possible to adjust the elastic modulus of

the adhesive resin layer (B) in a desired predetermined numerical range, without being particularly limited. However, from the viewpoint of the elastic modulus of the adhesive resin layer (B) and the initial peeling force, the blending ratio is preferably 1 to 100 parts by mass with respect to 100 parts by mass of the adhesive resin (B1). When the blending ratio of the tackifying resin is the lower limit value described above or more with respect to 100 parts by mass of the adhesive resin (B1), the adhesion with the support substrate during work tends to be good. On the other hand, when the blending ratio is the upper limit value described above or less, the sticking property to the support substrate at room temperature tends to be good. From the viewpoint of adhesion to the support substrate and sticking property at room temperature, the blending ratio of the tackifying resin is more preferably 2 to 50 parts by mass with respect to 100 parts by mass of the adhesive resin (B1). In addition, the acid value of the tackifying resin is preferably 30 or less. If the acid value of the tackifying resin is the upper limit value described above or less, adhesive residue tends to be less likely to occur on the support substrate during peeling.

[0071]

The thickness of the adhesive resin layer (B) is not particularly limited, but, for example, is preferably 5 μm or more and 300 μm or less, and more preferably 20 μm or more and 150 μm or less.

[0072]

It is possible to form the adhesive resin layer (B), for example, by a method for coating an adhesive coating solution on the base material layer 10, a method for transferring the adhesive resin layer

(B) formed on the separator onto the base material 10, and the like.

As a method for coating the adhesive coating solution, it is possible to adopt a coating method known in the related art, for example, a roll coater method, a reverse roll coater method, a gravure
5 roll method, a bar coating method, a comma coater method, a die coater method, or the like. The drying conditions of the coated adhesive are not particularly limited, but, generally, drying for 10 seconds to 10 minutes in a temperature range of 80 to 200°C is preferable. More preferably, drying is performed at 80 to 170°C for 15 seconds
10 to 5 minutes. In order to sufficiently accelerate the cross-linking reaction between the cross-linking agent and the adhesive, the adhesive coating solution may be heated at 40 to 80°C for approximately 5 to 300 hours after drying.

In addition, the base material layer 10 and the adhesive resin
15 layer (B) may be formed by coextrusion molding, or the film-shaped base material layer 10 and the film-shaped adhesive resin layer (B) may be formed by laminating (laminated).

[0073]

<Other Layers>

20 The adhesive film 50 according to the present embodiment may be further provided with, for example, an uneven absorption layer, a shock absorption layer, an easy-adhesion layer, or the like, between the base material layer 10 and the adhesive resin layer (A) or between the base material layer 10 and the adhesive resin layer (B) as long
25 as the effect of the present embodiment is not impaired.

[0074]

The uneven absorption layer is preferably formed of a natural

rubber, a synthetic rubber, or a synthetic resin having rubber elasticity having a Shore D type hardness according to D type Shore of ASTM D-2240 of, for example, 50 or less, preferably 40 or less. The thickness of the uneven absorption layer is, for example, 500
5 μm or less, preferably 5 to 300 μm , and more preferably 10 to 150 μm .

[0075]

Examples of the synthetic rubber and synthetic resin include nitrile-based, diene-based and acrylic-based synthetic rubbers,
10 polyolefin-based and polyester-based thermoplastic elastomers, synthetic resins having elasticity such as ethylene/vinyl acetate copolymers, polyurethane, polybutadiene, and soft polyvinyl chloride. Here, in the present embodiment, even with an essentially hard polymer such as polyvinyl chloride, it is also possible to use an example
15 which has rubber elasticity in combination with a compounding agent such as a plasticizer or a softener. In addition, it is possible to preferably use the adhesive resins and the like exemplified in the adhesive resin layer (A) and adhesive resin layer (B) described above for forming the uneven absorption layer.

20 [0076]

2. Electronic device Manufacturing Method

Next, a description will be given of a method for manufacturing the electronic device according to the present embodiment. Figs. 2 and 3 are cross-sectional views schematically showing an example
25 of a method for manufacturing an electronic device of an embodiment according to the present invention.

The electronic device manufacturing method according to the

present embodiment is provided with at least the following four steps.

(1) A step of preparing a structure 100 provided with the adhesive film 50, an electronic component 70 attached to the adhesive resin layer (A) of the adhesive film 50, and the support substrate 80 attached to an adhesive resin layer (B) of the adhesive film 50

(2) A step of sealing the electronic component 70 with a sealing material 60

(3) A step of peeling the support substrate 80 from the structure 100 by decreasing the adhesive force of the adhesive resin layer (B) by applying an external stimulus

(4) A step of peeling the adhesive film 50 from the electronic component 70

Then, in the method for manufacturing the electronic device according to the present embodiment, the adhesive film 50 according to the present embodiment described above is used as the adhesive film for temporarily fixing the electronic component 70.

[0077]

A description will be given below of each step of the method for manufacturing an electronic device according to the present embodiment.

[0078]

(Step (1))

First, A structure 100 is prepared which is provided with the adhesive film 50, the electronic component 70 attached to the adhesive resin layer (A) of the adhesive film 50, and the support substrate 80 attached to the adhesive resin layer (B) of the adhesive film 50.

[0079]

It is possible to manufacture the structure 100, for example, by the following procedure.

First, the adhesive film 50 is attached onto the support substrate 80 such that the adhesive resin layer (B) is on the support substrate 80 side. A protective film may be attached on the adhesive resin layer (B), and it is possible to peel off the protective film and to attach the exposed surface of the adhesive resin layer (B) to the surface of the support substrate 80.

As the support substrate 80, for example, it is possible to use a quartz substrate, a glass substrate, a SUS substrate, or the like.
[0080]

Next, it is possible to obtain the structure 100 by arranging the electronic component 70 on the adhesive resin layer (A) of the adhesive film 50 attached on the support substrate 80.

Examples of the electronic component 70 include a semiconductor chip such as an IC, an LSI, a discrete, a light emitting diode, or a light receiving element, a semiconductor panel, a semiconductor package, or the like.
[0081]

(Step (2))

Next, the electronic component 70 is sealed with the sealing material 60.

The electronic component 70 is covered with the sealing material 60, and the electronic component 70 is sealed by curing the sealing material 60 at a temperature of 150°C or lower, for example.

In addition, the form of the sealing material 60 is not particularly limited, but is, for example, a granular form, a sheet

form, or a liquid form.

[0082]

The sealing material 60 is not particularly limited, but, for example, it is possible to use an epoxy resin-based sealing material
5 using an epoxy resin.

In particular, a liquid epoxy resin-based sealing material is preferable from the viewpoint of improving the affinity of the sealing material 60 with the adhesive film 50 and being able to more evenly seal the electronic component 70.

10 As such an epoxy resin-based sealing material, for example, it is possible to use the T693/R4000 series, T693/R1000 series, T693/R5000 series, and the like manufactured by Nagase Chemtex Corp.

[0083]

Examples of the sealing method include transfer molding,
15 injection molding, compression molding, cast molding, and the like. After sealing the electronic component 70 with the sealing material 60, for example, the sealing material 60 is cured by heating at a temperature of 150°C or less and the structure 100 in which the electronic component 70 is sealed is obtained.

20 [0084]

(Step (3))

Next, the adhesive force of the adhesive resin layer (B) is decreased by applying an external stimulus and the support substrate 80 is peeled from the structure 100.

25 It is possible to easily remove the support substrate 80 from the adhesive film 50 by, for example, sealing the electronic component 70 and then heating at a temperature over 150°C to decrease the adhesive

force of the adhesive resin layer (B).

[0085]

(Step (4))

Next, the adhesive film 50 is removed from the electronic
5 component 70 to obtain the electronic device 200.

Examples of a method for removing the adhesive film 50 from the
electronic component 70 include a mechanical peeling method, a method
for decreasing the adhesive force of the surface of the adhesive film
50 and then peeling the adhesive film 50, and the like.

10 [0086]

(Step (5))

As shown in Fig. 3, the method for manufacturing an electronic
device according to the present embodiment may be further provided
with a step (5) of forming a wiring layer 310 and a bump 320 on an
15 exposed surface of the obtained electronic device 200 to obtain the
electronic device 300.

[0087]

The wiring layer 310 is provided with a pad (not shown) which
is an external connection terminal formed on the outermost surface,
20 and wiring (not shown) which electrically connects the exposed
electronic component 70 and the pad. It is possible to form the wiring
layer 310 by a method known in the related art and the structure thereof
may be multi-layer.

[0088]

25 Then, it is possible to obtain the electronic device 300 by
forming the bump 320 on the pad of the wiring layer 310. Examples
of the bump 320 include a solder bump, a gold bump, and the like.

It is possible to form the solder bump, for example, by arranging a solder ball on a pad which is an external connection terminal of the wiring layer 310 and carrying out heating to melt (reflow) the solder.

5 It is possible to form the gold bump by methods such as a ball bonding method, a plating method, or an Au ball transfer method.

[0089]

(Step (6))

10 The electronic device manufacturing method according to the present embodiment may be further provided with a step (6) of dicing the electronic device 300 to obtain a plurality of electronic devices 400, as shown in Fig. 3.

It is possible to perform the dicing of the electronic device 300 by a known method.

15 [0090]

A description was given above of the embodiments of the present invention, but these are Examples of the present invention and it is also possible to adopt various configurations other than the above.

[0091]

20 Here, the present invention is not limited to the embodiments described above and modifications, improvements, and the like in a range in which it is possible to achieve the object of the present invention are included in the present invention.

[Examples]

25 [0092]

A specific description will be given below of the present invention with reference to Examples, but the present invention is

not limited thereto.

[0093]

Details of the materials used to manufacture the adhesive film are as follows.

5 [0094]

<Adhesive Resin Solution SA1>

Into deionized pure water, 0.5 parts by mass of 4,4'-azobis-4-cyanovaleric acid (manufactured by Otsuka Chemical Co., Ltd.; trade name: ACVA) as a polymerization initiator, 78 parts by mass of n-butyl acrylate and 10 parts by mass of methyl methacrylate as the monomer (a1), 9 parts by mass of 2-hydroxyethyl methacrylate as the monomer (a2), and 3 parts by mass of a polymerizable surfactant in which a polymerizable 1-propenyl group was introduced into a benzene ring of ammonium salt of sulfuric acid ester of polyoxyethylene nonylphenyl ether (manufactured by DKS Co., Ltd.; trade name: Aqualon HS-1025) were each added, and emulsion polymerization was carried out for 8 hours at 70 to 72°C while stirring to obtain an acrylic-based resin emulsion. The result was neutralized with aqueous ammonia (pH = 7.0) to obtain an adhesive resin solution SA1 having a solid content concentration of 42.5%.

20 [0095]

<Adhesive Resin Solution SA2>

Into deionized pure water, 0.5 parts by mass of ammonium persulfate as a polymerization initiator, 61 parts by mass of 2-ethylhexyl acrylate, 20 parts by mass of acrylic acid-n-butyl, and 9 parts by mass of methyl methacrylate as the monomer (a1), 3 parts by mass of 2-hydroxyethyl methacrylate as the monomer (a2), 1 part

by mass of polytetramethylene glycol diacrylate (manufactured by NOF Corp.; trade name; ADT-250) as a monomer (a3), and 2 parts by mass of a polymerizable surfactant in which a polymerizable 1-propenyl group was introduced into a benzene ring of an ammonium salt of a
5 sulfuric acid ester of polyoxyethylene nonylphenyl ether (manufactured by DKS Co., Ltd.; trade name: Aqualon HS-1025) were each added, and emulsion polymerization was carried out for 8 hours at 70 to 72°C while stirring to obtain an acrylic-based resin emulsion. The result was neutralized with aqueous ammonia (pH = 7.0) to obtain
10 an adhesive resin solution SA2 having a solid content concentration of 56.5%.

[0096]

<Adhesive Coating Solution A1>

55 parts by mass of adhesive resin solution SA1, 45 parts by
15 mass of adhesive resin solution SA2, 0.5 parts by mass of dimethylethanolamine, and 4 parts by mass of an epoxy-based compound (Ex-1610, manufactured by Nagase Chemtex Corp.) as a cross-linking agent were mixed together to obtain an adhesive coating solution A1.

[0097]

20 <Adhesive Resin Solution SB1>

In a mixed solvent including ethyl acetate and toluene, 0.5 parts by mass of t-butylperoxy-2-ethylhexanoate (manufactured by NOF Corp.; trade name: Perbutyl O (registered trademark)) as a polymerization initiator, 35 parts by weight of 2-ethylhexyl acrylate,
25 40 parts by mass of acrylic acid-n-butyl, and 15 parts by mass of ethyl acrylate as monomer (b1), 10 parts by mass of 2-hydroxyethyl methacrylate as monomer (b2) were each added and solution

polymerization was carried out at 83 to 87°C for 11 hours while stirring to obtain an acrylic-based resin solution having a solid content concentration of 45% by mass. The result was set as the adhesive resin solution SB1.

5 [0098]

<Adhesive Coating Solution B1>

100 parts by mass of the adhesive resin solution SB1 and 0.9 parts by mass (2 parts by mass with respect to 100 parts by mass of the adhesive resin) of an isocyanate-based cross-linking agent (manufactured by Mitsui Chemicals, Inc.; trade name: Olester P49-75S) were each mixed and the solid content concentration was adjusted to 40% with ethyl acetate to obtain an adhesive coating solution B1.

[0099]

<Adhesive Coating Solution B2>

15 100 parts by mass of the adhesive resin solution SB1, 2.25 parts by weight of a polymerized rosin ester-based tackifier (manufactured by Arakawa Chemical Industries, Ltd.; trade name: Pensel D-125) (5 parts by mass with respect to 100 parts by mass of adhesive resin), 1.2 parts by mass of an isocyanate-based cross-linking agent (manufactured by Mitsui Chemicals, Inc.; trade name: Olester P49-75S) (2 parts by mass with respect to 100 parts by mass of adhesive resin), 6.75 parts by mass of heat-expandable microspheres (Sekisui Chemical Co., Ltd.; trade name: Advancell EM-503) (15 parts by mass with respect to 100 parts by mass of the adhesive resin) were each mixed and the solid content concentration was adjusted to 30% with ethyl acetate to prepare an adhesive coating solution B2.

[0100]

<Adhesive Resin Solution SB2>

In a mixed solvent including ethyl acetate and toluene, 0.25 parts by mass of t-butylperoxy-2-ethylhexanoate (manufactured by NOF Corp.; trade name: Perbutyl O (registered trademark)) as a
5 polymerization initiator, 72 parts by mass of acrylic acid-n-butyl as the monomer (b1), 18 parts by mass of methyl methacrylate, 7 parts by mass of 2-hydroxyethyl methacrylate as the monomer (b2), and 3 parts by mass of acrylic acid were each added and solution
10 polymerization was carried out at 83 to 87°C for 11 hours while stirring to obtain an acrylic-based resin solution having a solid content concentration of 45% by mass. The result was set as the adhesive resin solution SB2.

[0101]

<Adhesive Coating Solution B3>

15 100 parts by mass of the adhesive resin solution SB2, 0.05 parts by mass of dimethylethanolamine, and 1.35 parts by mass of epoxy-based cross-linking agent (Ex-614 manufactured by Nagase Chemtex Corp.) (3 parts by mass with respect to 100 parts by mass of the adhesive resin) were each mixed and the solid content concentration was
20 adjusted to 40% with ethyl acetate to obtain an adhesive coating solution B3.

[0102]

<Adhesive Coating Solution B4>

25 100 parts by mass of the adhesive resin solution SB2, 2.25 parts by weight of a polymerized rosin ester-based tackifier (manufactured by Arakawa Chemical Industries, Ltd.; trade name: Pensel D-125) (5 parts by mass with respect to 100 parts by mass of adhesive resin),

1.2 parts by mass of an epoxy-based cross-linking agent (manufactured by Nagase Chemtex Corp., Ex-1610) (2 parts by mass with respect to 100 parts by mass of adhesive resin), 9 parts by mass of heat-expandable microspheres (Sekisui Chemical Co., Ltd.; trade name: Advancell EM-503) (20 parts by mass with respect to 100 parts by mass of the adhesive resin) were each mixed, and the solid content concentration was adjusted to 30% with ethyl acetate to prepare an adhesive coating solution B4.

[0103]

10 <Adhesive Resin Coating Solution B5>

100 parts by mass of the adhesive resin solution SB2 and 1 part by mass of an ester-based cross-linking agent (manufactured by Mitsubishi Gas Chemical Company, Inc., solid content concentration 100%, Tetrad-C) were each mixed, and the solid content concentration was adjusted to 30% with ethyl acetate to prepare an adhesive coating solution B5.

[0104]

<Adhesive Resin Coating Solution B6>

100 parts by mass of adhesive resin solution SB2, 2.25 parts by weight of a polymerized rosin ester-based tackifier (manufactured by Arakawa Chemical Industries, Ltd.; trade name: Pensel D-125) (5 parts by mass with respect to 100 parts by mass of the adhesive resin), 1.2 parts by mass of an epoxy-based cross-linking agent (manufactured by Mitsubishi Gas Chemical Company, Inc., solid content concentration 100%, Tetrad-C) (2 parts by mass with respect to 100 parts by mass of the adhesive resin), 9 parts by mass of heat-expandable microspheres (manufactured by Sekisui Chemical Co., Ltd.; trade name:

Advancell EM-503) (20 parts by mass with respect to 100 parts by mass of the adhesive resin) were each mixed and the solid content concentration was adjusted to 30% with ethyl acetate to prepare an adhesive coating solution B6.

5 [0105]

[Example 1]

The adhesive coating solution A1 was coated on a polyethylene terephthalate (PET) film (thickness 38 μm), which is a base material layer, and then dried to form the adhesive resin layer (A) with a
10 thickness of 10 μm . Then, the adhesive coating solution B1 is coated on the surface of the PET film on the opposite side to the adhesive resin layer (A) via a separator and dried to form an uneven absorption layer with a thickness of 20 μm , then an adhesive resin layer (B) with a thickness of 25 μm formed from the adhesive coating solution
15 B2 was provided thereon to obtain an adhesive film having the adhesive resin layer (B). The adhesive resin layer (B) was formed by a method for forming the layer on a separate separator and transferring the layer onto the uneven absorption layer.

The following evaluation was performed on the obtained adhesive
20 film. The obtained results are shown in Table 1.

[0106]

[Example 2]

An adhesive film was obtained in the same manner as in Example 1 except that the adhesive coating solution B3 was used instead of
25 the adhesive coating solution B1 and the adhesive coating solution B4 was used instead of the adhesive coating solution B2.

The following evaluation was performed on the obtained adhesive

film. The obtained results are shown in Table 1.

[0107]

[Comparative Example 1]

An adhesive film was obtained in the same manner as in Example
5 1 except that the adhesive resin solution B5 was used instead of the
adhesive coating solution B1 and the adhesive coating solution B6
was used instead of the adhesive coating solution B2.

The following evaluation was performed on the obtained adhesive
film. The obtained results are shown in Table 1.

10 [0108]

<Evaluation>

(1) Measurement of Integrated tacking force values $F_{2.5}$ and F_{30}
Using a tacking tester TAC-II manufactured by RHESCA, under the
conditions of a probe load of 100 gf and a probe pushing speed of
15 120 mm/min, a probe was pressed for 60 seconds on the adhesive resin
layer (B) of the adhesive films obtained in the Examples and
Comparative Examples. Next, the tack strength (gf) was measured at
a test temperature of 130°C and test speeds of 2.5 mm/min and 30 mm/min,
respectively. Here, the measurement time was set on the horizontal
20 axis and the tack strength (gf) was set on the vertical axis, and
the integrated values were calculated respectively from the point
where the tack strength started to rise from 0 to the point where
the tack strength returns to 0 again, and the obtained values were
set to $F_{2.5}$ [gf/sec] and F_{30} [gf/sec], respectively.

25 [0109]

(2) Position Shifting of Electronic Components in Sealing Step

The adhesive resin layer (B) side of the adhesive films obtained

in Examples and Comparative Examples was bonded onto a stainless steel plate ($\phi 310$ mm, thickness 1.5 mm) for compression molding, semiconductor chips with a size of 5.0 mm square as electronic components were mounted and adhered on the adhesive resin layer (A) of the adhesive film so as to be in a grid pattern with an interval of 2.0 mm to obtain a structure.

Next, using a compression molding machine, a plurality of semiconductor chips on the adhesive resin layer (A) were sealed by compression molding with a liquid epoxy resin-based sealing material (manufactured by Nagase Chemtex Corp., trade name: T693/R4212-2C) to obtain a structure in which a sealing resin wafer ($\phi 300$ mm, thickness 0.5 mm) was formed on a stainless steel plate.

Next, the position shifting of the electronic components was evaluated based on the following criteria.

No shifting: no position shifting of the semiconductor chip was visually observed

Shifting: position shifting was visually observed in at least part of the semiconductor chip

[0110]

(3) Heat Peelability after Sealing Step

The adhesive resin layer (B) side of the 10 cm $\times$ 10 cm adhesive film obtained in the Examples and Comparative Examples was pressed at a pressure of 0.5 MPa and bonded on a mirror-finished stainless steel plate (SUS304BA sheet) having a length of 10 cm $\times$ width of 10 cm $\times$ thickness of 1 mm. Next, the obtained structure was subjected to a heat treatment at 140°C for 60 minutes to stabilize the adhesive force of the adhesive resin layer (A) and the adhesive resin layer

(B). Next, the structure was cooled to room temperature.

Next, after heating the structure on a hot plate at 190°C for 2 minutes, the adhesive film was peeled from the stainless steel plate under conditions of 23°C and a tensile speed of 300 mm/min, and the 180° peel force was measured.

The possibility of heat peeling the adhesive film from the stainless steel plate was evaluated based on the following criteria.

Possible: 180° peel force of less than 0.5 N/25 mm

Not possible: 180° peel force of 0.5N/25 mm or more

10 [0111]

[Table 1]

	$F_{2.5}$ [gf/sec]	F_{30} [gf/sec]	Position shifting of semiconductor chip	Peeling possibility
Example 1	3.9	14.1	No shifting	Possible
Example 2	3.3	18.2	No shifting	Possible
Comparative Example 1	0.8	5.6	Shifting	Possible

[0112]

In the Examples using an adhesive film having an integrated tacking force value ($F_{2.5}$) of 1.0 gf/sec or more and an integrated tacking force value (F_{30}) of 7.0 gf/sec or more, no position shifting of the semiconductor element was observed in the sealing step. Thus, it is understood that the adhesive films of Examples were able to suppress the position shifting of the electronic component in the sealing step.

20 On the other hand, in Comparative Examples using an adhesive film having an integrated tacking force value ($F_{2.5}$) of less than 1.0

gf/sec and an integrated tacking force value (F_{30}) of less than 7.0 gf/sec, the position shifting of the semiconductor element was observed in the sealing step. Thus, in the adhesive film of the Comparative Examples, it is understood that position shifting of the electronic component was generated in the sealing step.

[0113]

This application claims priority based on Japanese Patent Application No. 2018-061342 filed on March 28, 2018, and all of the disclosure thereof is incorporated herein.

CLAIMS

1. An adhesive film comprising:

a base material layer;

5 an adhesive resin layer (A) provided on a first surface side of the base material layer; and

an adhesive resin layer (B) provided on a second surface side of the base material layer and in which an adhesive force is decreased by an external stimulus,

10 wherein, as measured by method 1, an integrated tacking force value ($F_{2.5}$) of the adhesive resin layer (B) is 1.0 gf/sec or more at a test speed of 2.5 mm/min and a test temperature of 130°C, and an integrated tacking force value (F_{30}) of the adhesive resin layer (B) is 7.0 gf/sec or more at a test speed of 30 mm/min and a test
15 temperature of 130°C,

(method 1) using a tacking tester, a probe is pressed on the adhesive resin layer (B) for 60 seconds under conditions of a probe load of 100 gf and a probe pushing speed of 120 mm/min, then, at a test temperature of 130°C, tack strengths (gf) are respectively
20 measured at test speeds of 2.5 mm/min and 30 mm/min, a measurement time is set as a horizontal axis and the tack strength (gf) is set as a vertical axis, integrated values are each calculated from a point where the tack strength starts to rise from 0 to a point where the tack strength becomes 0 again, and the calculated values are
25 respectively set as $F_{2.5}$ and F_{30} .

2. The adhesive film according to claim 1,

wherein the adhesive film is used for temporarily fixing an electronic component when the electronic component is sealed with a sealing material in an electronic device manufacturing step.

5 3. The adhesive film according to claim 1 or 2,

wherein an adhesive force of the adhesive resin layer (B) is decreased by heating at a temperature over 150°C.

4. The adhesive film according to claim 3,

10 wherein the adhesive resin layer (B) includes at least one selected from a gas generating component and a heat-expandable microsphere.

5. The adhesive film according to any one of claims 1 to 4,

15 wherein a content of at least one selected from a gas generating components and a heat-expandable microsphere in the adhesive resin layer (A) is 0.1% by mass or less when an entire adhesive resin layer (A) is 100% by mass.

20 6. The adhesive film according to any one of claims 1 to 5,

wherein the adhesive resin layer (A) includes a (meth)acrylic adhesive resin.

7. A method for manufacturing an electronic device comprising at
25 least:

a step (1) of preparing a structure having the adhesive film according to any one of claims 1 to 6, an electronic component attached

to the adhesive resin layer (A) of the adhesive film, and a support substrate attached to the adhesive resin layer (B) of the adhesive film;

5 a step (2) of sealing the electronic component with a sealing material;

a step (3) of peeling the support substrate from the structure by decreasing an adhesive force of the adhesive resin layer (B) by applying an external stimulus; and

10 a step (4) of peeling the adhesive film from the electronic component.

8. The method for manufacturing an electronic device according to claim 7,

15 wherein the sealing material is an epoxy resin-based sealing material.